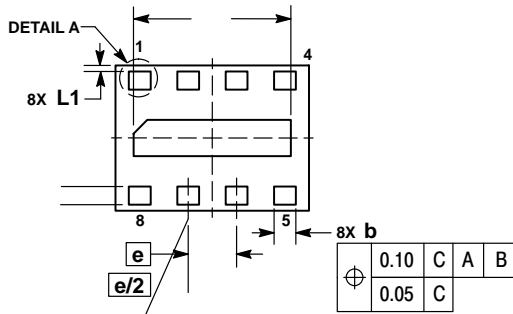
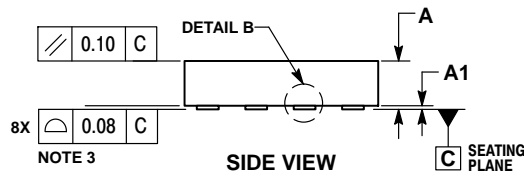
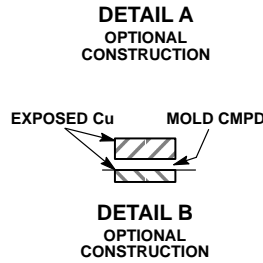
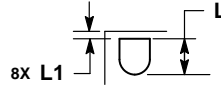
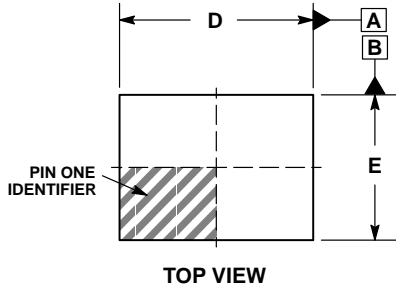




XDFN8 1.6x1.2, 0.4P
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ISSUE D

DATE 08 DEC 2015

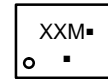


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	NOM
A	0.300	0.375
A1	0.000	0.025
b	0.130	0.180
D		
D2	1.200	1.300
E		
E2	0.200	0.300
e	0.40 BSC	
L	0.150	0.200
L1		

GENERIC MARKING DIAGRAM*



- XX = Specific Device Code
- M = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)

may additionally reference the ON Semiconductor website for more information. For details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

RECOMMENDED MOUNTING FOOTPRINT*

